



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takayuki USAMI et al.

Serial No.: 09/966,389

Group Art Unit: 1742

Filed: September 27, 2001

Examiner: Sikyin Ip

For: HIGH MECHANICAL STRENGTH COPPER ALLOY

SUPPLEMENTAL AMENDMENT

RECEIVED

SEP 4 - 2002
TC 1700

August 30, 2002

Commissioner for Patents
Washington, D.C. 20231

Sir:

In supplement to the Office Action Response, filed June 12, 2002, please amend the above-identified application as indicated below.

IN THE CLAIMS

Please amend claims 1, 5, 12, 14, 16 and 18 as follows:

1. (Twice Amended) A high-mechanical strength copper alloy, consisting essentially of 3.5 to 4.5% by mass of Ni, 0.7 to 1.0% by mass of Si, 0.01 to 0.20% by mass of Mg, 0.05 to 1.5% by mass of Sn, 0.2 to 1.5% by mass of Zn, and less than 0.005% by mass (including 0% by mass) of S, with the balance being made of Cu and inevitable impurities,

wherein a diameter of a crystal grain in the alloy is from more than 0.001 mm to 0.025 mm; and the ratio (a/b), between a longer diameter a of a crystal grain on a cross section parallel to a direction of final plastic working, and a longer diameter b of a crystal grain on a cross section perpendicular to the direction of final plastic working, is 1.5 or less,

wherein the alloy has a tensile strength of 800 N/mm² or more, and